

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	94	257/\$.ccls. and (chip die ic) adj2 controller same (substrate board carrier)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/06/26 16:40	
2	BRS	L2	136	257/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (gap disconnect\$3)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/06/26 17:09	
3	BRS	L3	16	("5045921" "5048664" "5216278" "5218378" "5410124" "5451721" "5602422" "5642265" "5766021" "5791552" "5828128" "5835355" "5849130" "6064576" "6069407" "6139972") .PN.	USPA T	2004/06/26 16:47	
4	BRS	L4	26	174/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (gap disconnect\$3)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/06/26 16:52	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	L5	43	438/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (gap disconnect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 16:53	
6	BRS	L6	11	29/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (gap disconnect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 16:54	
7	BRS	L10	2529	programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 16:59	
8	BRS	L11	184	257/\$.ccls. and programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:04	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
9	BRS	L12	31	174/\$.ccls. and programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; ;EPO; JPO; DERWENT; IBM_TDB	2004/06/26 17:06	
10	BRS	L13	47	438/\$.ccls. and programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; ;EPO; JPO; DERWENT; IBM_TDB	2004/06/26 17:07	
11	BRS	L14	11	29/\$.ccls. and programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; ;EPO; JPO; DERWENT; IBM_TDB	2004/06/26 17:08	
12	BRS	L15	54	361/\$.ccls. and programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; ;EPO; JPO; DERWENT; IBM_TDB	2004/06/26 17:08	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
13	BRS	L16	210	257/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (space void)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:14	
14	BRS	L17	43	174/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (space void)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:16	
15	BRS	L18	93	438/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (space void)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:18	
16	BRS	L19	47	361/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (space void)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:19	